

### Features

- Guard Ring Die Construction for Transient Protection
- Low Power Loss, High Efficiency
- Patented Interlocking Clip Design for High Surge Current Capacity
- High Current Capability and Low Forward Voltage Drop
- **Lead Free Finish, RoHS Compliant (Note 4)**
- **"Green" Molding Compound (No Br, Sb)**
- **Qualified to AEC-Q101 Standards for High Reliability**

### Mechanical Data

- Case: PowerDI®123
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminal Connections: Cathode Band
- Terminals: Finish – Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208 (E3)
- Marking Information: See Page 2
- Ordering Information: See Page 2
- Weight: 0.01 grams (approximate)



Top View

### Maximum Ratings @T<sub>A</sub> = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load.  
 For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V <sub>RRM</sub>	20	V
Working Peak Reverse Voltage	V <sub>RWM</sub>		
DC Blocking Voltage	V <sub>R</sub>		
RMS Reverse Voltage	V <sub>R(RMS)</sub>	14	V
Average Forward Current	I <sub>F(AV)</sub>	1.0	A
Non-Repetitive Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load	I <sub>FSM</sub>	50	A

### Thermal Characteristics

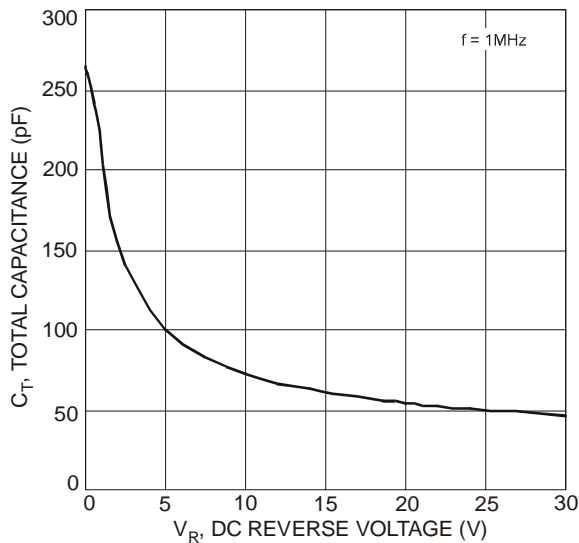
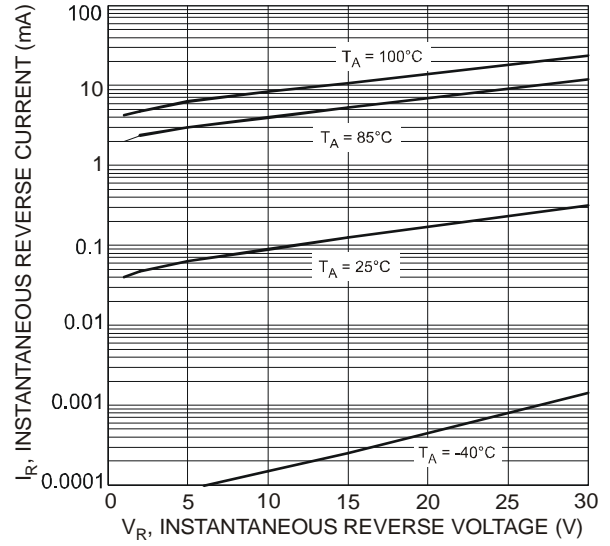
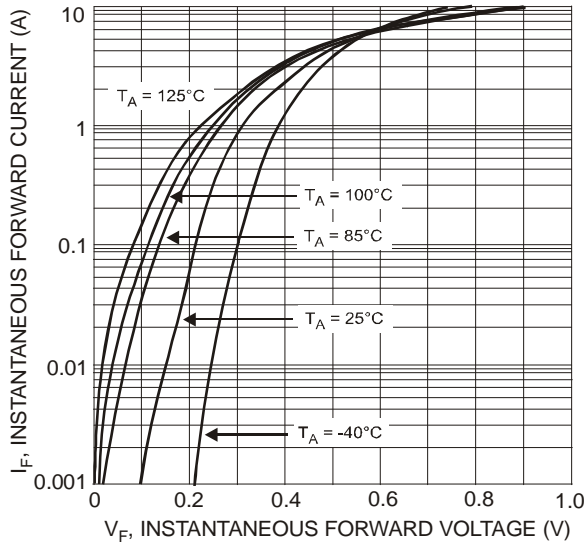
Characteristic	Symbol	Value	Unit
Power Dissipation (Note 1)	P <sub>D</sub>	1.67	W
Power Dissipation (Note 2)	P <sub>D</sub>	556	mW
Thermal Resistance Junction to Ambient (Note 1)	R <sub>θJA</sub>	60	°C/W
Thermal Resistance Junction to Ambient (Note 2)	R <sub>θJA</sub>	180	°C/W
Thermal Resistance Junction to Soldering (Note 3)	R <sub>θJS</sub>	10	°C/W
Operating Temperature Range	T <sub>J</sub>	-55 to +125	°C
Storage Temperature Range	T <sub>STG</sub>	-55 to +150	°C

### Electrical Characteristics @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 5)	V <sub>(BR)R</sub>	20	—	—	V	I <sub>R</sub> = 1.0mA
Forward Voltage	V <sub>F</sub>	—	0.20	—	V	I <sub>F</sub> = 0.1A
		—	0.30	—		I <sub>F</sub> = 0.7A
		—	0.32	0.36		I <sub>F</sub> = 1.0A
Leakage Current (Note 5)	I <sub>R</sub>	—	0.26	—	mA	V <sub>R</sub> = 5V, T <sub>A</sub> = 25°C
		—	—	1.0		V <sub>R</sub> = 20V, T <sub>A</sub> = 25°C
Total Capacitance	C <sub>T</sub>	—	75	—	pF	V <sub>R</sub> = 10V, f = 1.0MHz

- Notes:
1. Part mounted on 50.8mm X 50.8mm GETEK board with 25.4mm X 25.4mm copper pad, 25% anode, 75% cathode. T<sub>A</sub> = 25°C.
  2. Part mounted on FR-4 board with 1.8mm X 2.5mm cathode and 1.8mm X 1.2mm anode, 1 oz. copper pads. T<sub>A</sub> = 25°C.
  3. Theoretical R<sub>θJS</sub> calculated from the top center of the die straight down to the PCB/cathode tab solder junction.
  4. EU Directive 2002/95/EC (RoHS). All applicable RoHS exemptions applied, see *EU Directive 2002/95/EC Annex Notes*.
  5. Short duration pulse test used to minimize self-heating effect.

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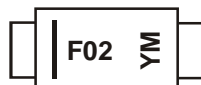


**Ordering Information** (Note 6)

Part Number	Case	Packaging
DFLS120L-7	PowerDI®123	3000/Tape & Reel

Notes: 6. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

**Marking Information**



F02 = Product Type Marking Code  
 YM = Date Code Marking  
 Y = Year (ex: T = 2006)  
 M = Month (ex: 9 = September)

Date Code Key

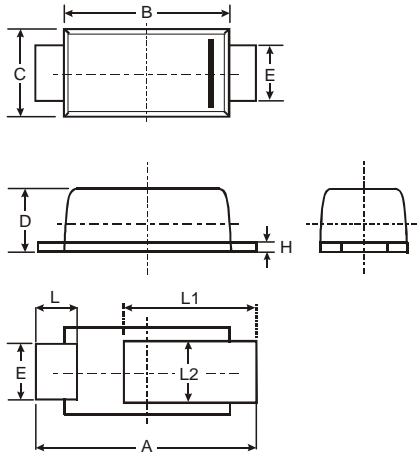
Year	2004	2005	2006	2007	2008	2009	2010	2011	2012
Code	R	S	T	U	V	W	X	Y	Z

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

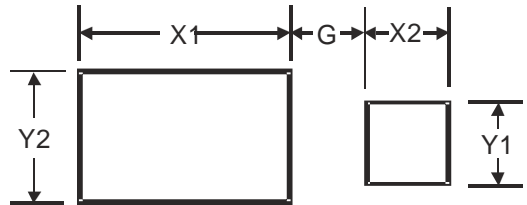
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**Package Outline Dimensions**



PowerDI <sup>123</sup>			
Dim	Min	Max	Typ
A	3.50	3.90	3.70
B	2.60	3.00	2.80
C	1.63	1.93	1.78
D	0.93	1.00	0.98
E	0.85	1.25	1.00
H	0.15	0.25	0.20
L	0.55	0.75	0.65
L1	1.80	2.20	2.00
L2	0.95	1.25	1.10
<b>All Dimensions in mm</b>			

**Suggested Pad Layout**



Dimensions	Value (in mm)
G	1.0
X1	2.2
X2	0.9
Y1	1.4
Y2	1.4

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